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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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# DB3S314J

## Silicon epitaxial planar type

For high speed switching circuits  
DB3J314J in SSMini3 type package

### ■ Features

- Short reverse recovery time  $t_{rr}$
- Small reverse current  $I_R$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

### ■ Marking Symbol: 4Y

### ■ Basic Part Number

Dual DB2J314 (Common Anode)

### ■ Packaging

DB3S314J0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Maximum peak reverse voltage	$V_{RM}$	30	V
Forward current	Single	30	mA
	Double *1	20	
Peak forward current	Single	150	mA
	Double *1	110	
Junction temperature	$T_j$	125	$^\circ\text{C}$
Operating ambient temperature	$T_{opr}$	-40 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

Note) \*1: Value of each diode in double diodes used.

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

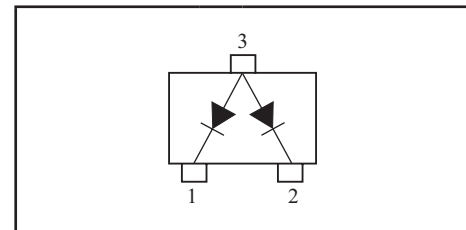
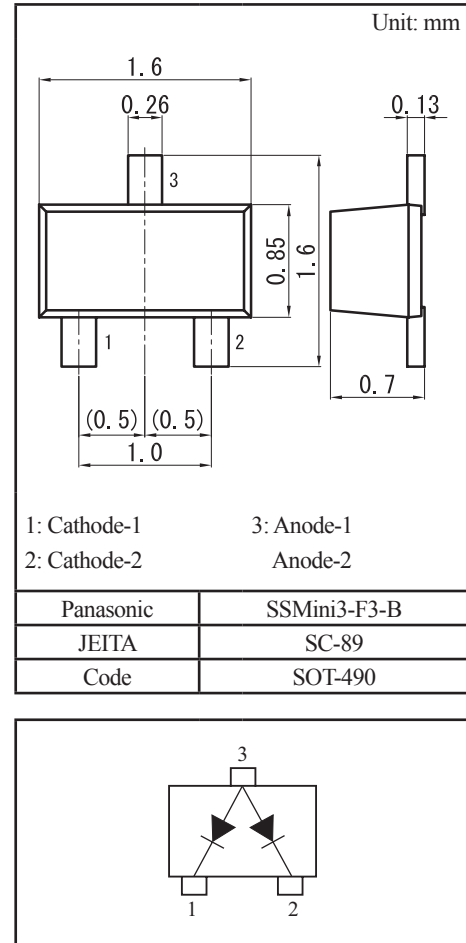
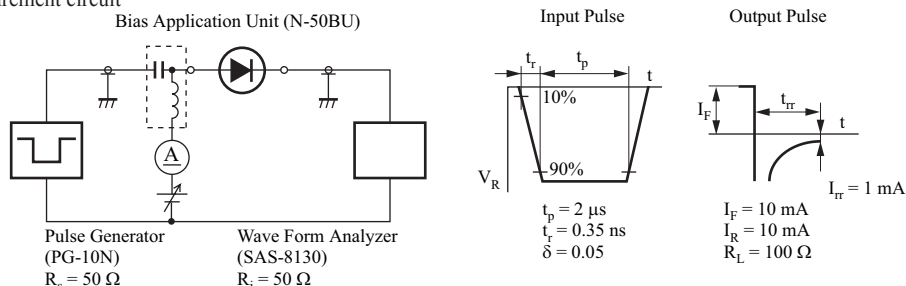
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 1 \text{ mA}$			0.4	V
	$V_{F2}$	$I_F = 30 \text{ mA}$			1.0	
Reverse current	$I_R$	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	$C_t$	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *1	$t_{rr}$	$I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$		1.0		ns

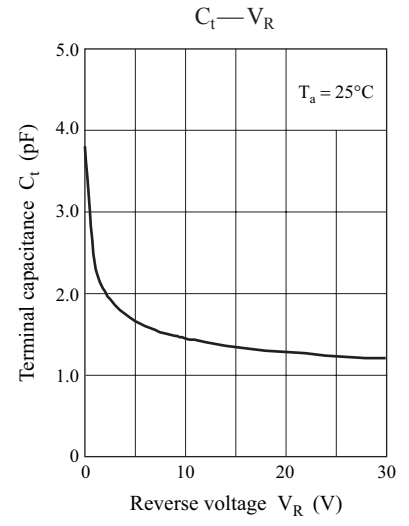
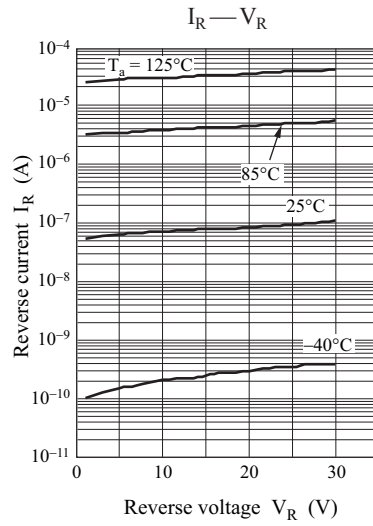
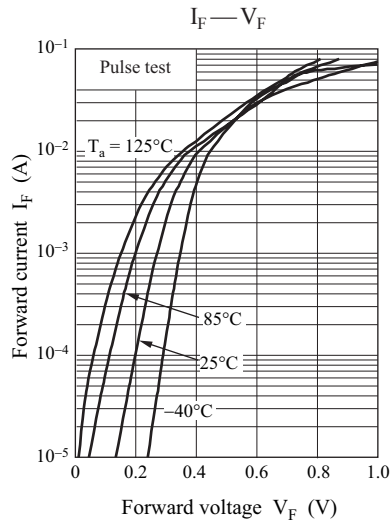
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 2 GHz

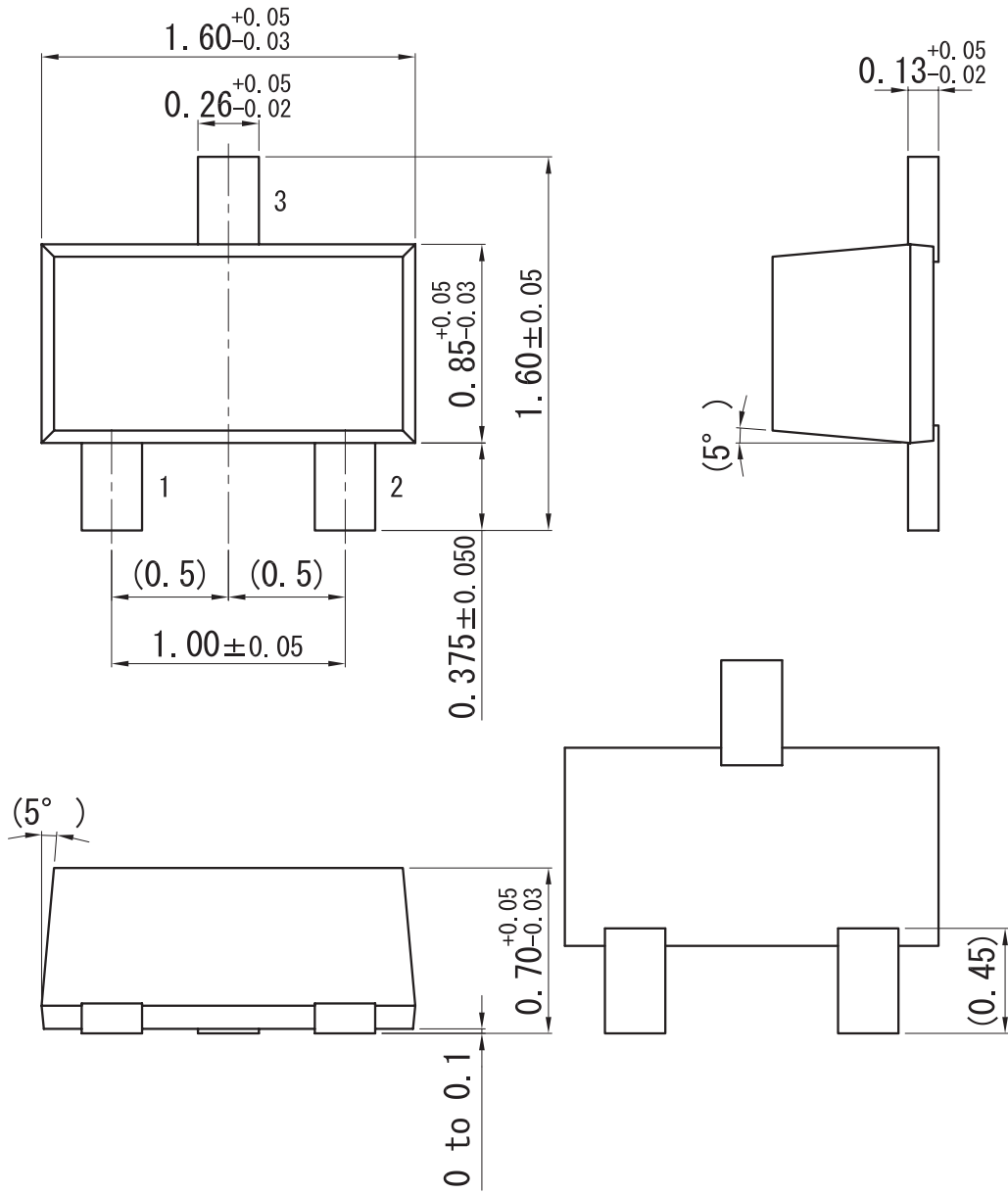
\*1:  $t_{rr}$  measurement circuit



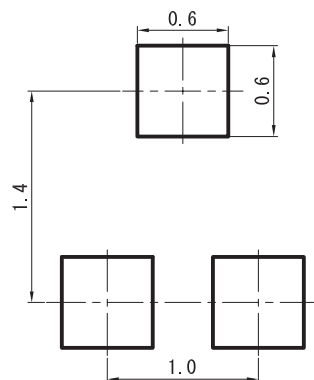


SSMini3-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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